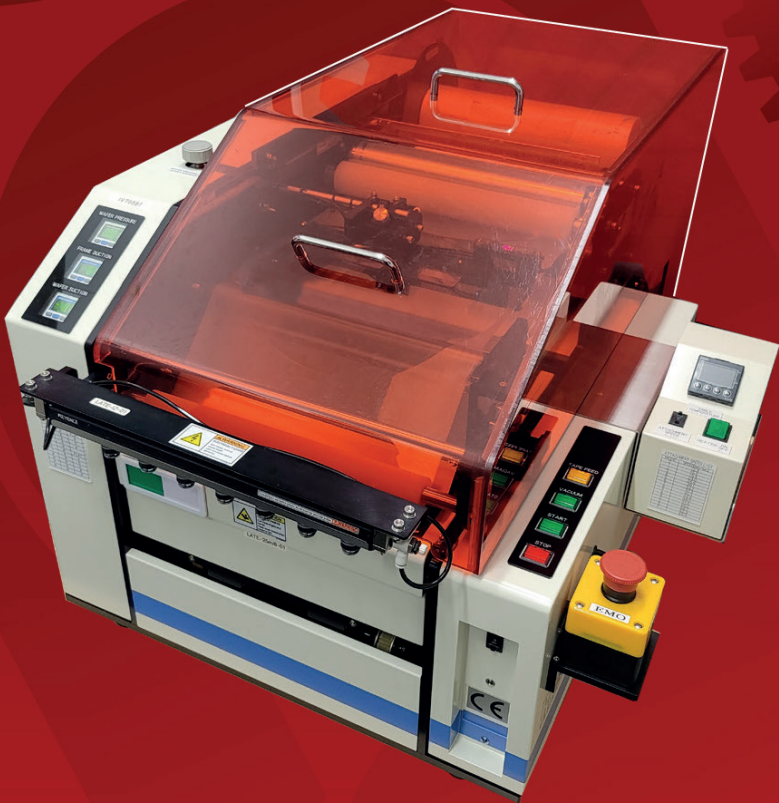


RELIABLE

Semi-Automatic
Wafer Mounter

**RAD-2500m
Series: 8 & 12**



-  Uses pre-cut tape
-  Ensured safety & easy to operate
-  Accurate & reliable mounting
-  Small footprint & high performance



LINTEC Corporation

BENEFITS



Uses pre-cut tape

LINTEC's semi-automatic dicing tape mounters enable easy operation by the use of pre-cut tapes. By simply placing a wafer and frame on the equipment's table, dicing tape mounting is automatically performed.



Ensured safety & easy to operate

Extremely safe handling, a user-friendly interface and increased operational efficiency as the equipment uses no cutting blade.



Accurate & reliable mounting

LINTEC's patented Tape Tension Control system (TTC) enables reliable tape mounting through prevention of air voids and application of controlled and individually adjustable tape tension.



Small footprint & high performance

Achieving highest quality mounting results, LINTEC's semi-automatic mounters accommodate the demand for a compact equipment with reliable performance and effective use of workspace.



Suited for low & medium volume production or R&D environments

ACCESSORIES

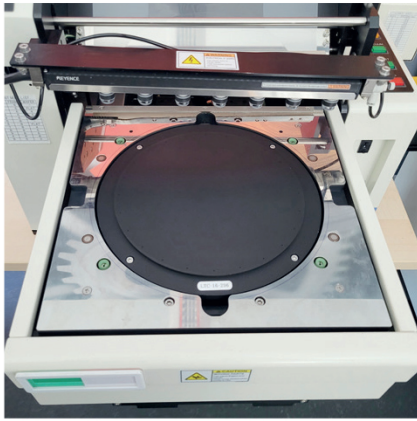
Example of available wafer-tables



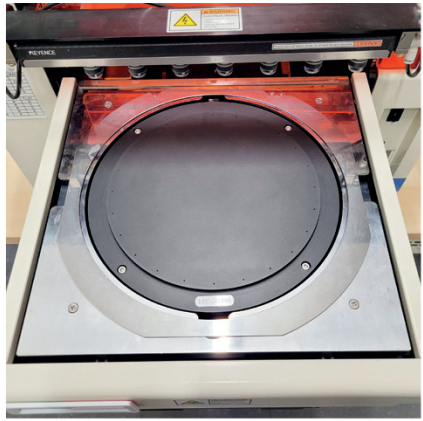
Full-contact table 8"



Non-contact table 8"



Full-contact table and
frame-table without frame



Full-contact table and
frame-table with *DISCO*
frame

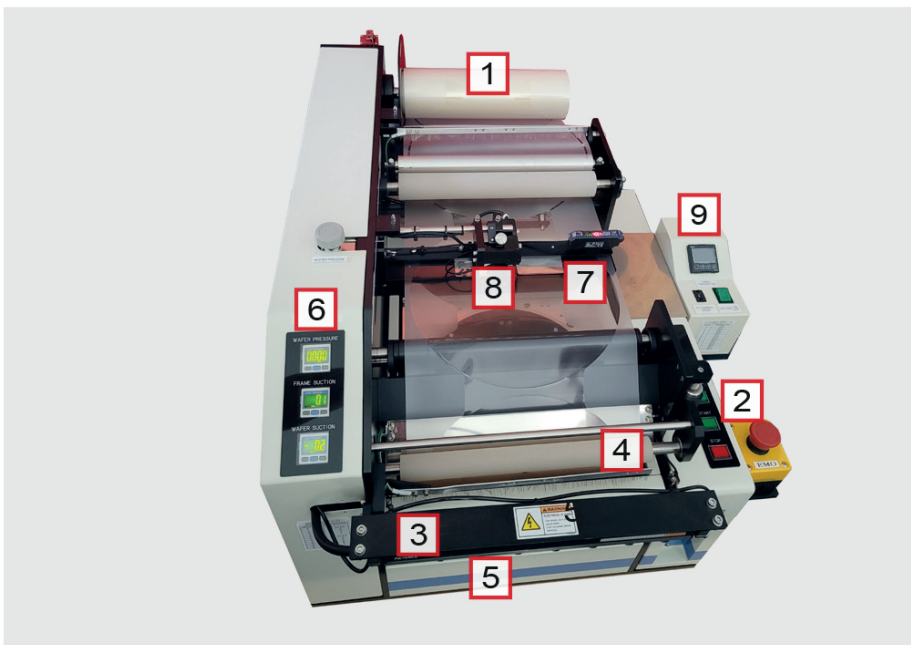
LINTEC offers several different full- and non-contact wafer-table options, customizable for various customer needs. Available in different materials, they can not only be tailored for different wafer-materials and shapes, but also for rectangular substrates or packages. An optional wafer-table heating function enhances wafer-backside embedding by the dicing tape.

All LINTEC wafer-tables are equipped with a vacuum-suction function to hold the wafer securely in place during the mounting process and can be selected to suit wafers with either V-Notch or Orientation Flat.

SPECIFICATION

	2500m/8	2500m/12
Wafer Sizes (mm)	200, 150, 125, 100	300, 200, 150
Ring Frames	8" and 6", DISCO & K&S	12" and 8", DISCO & K&S
Process capacity	~18 sec. per work-piece	~22 sec. per work-piece

MACHINE DESCRIPTION



- 1 Tape unwinder
- 2 EMO
- 3 Ionizer
- 4 Press roller
- 5 Retractable tape mounting unit
- 6 Displays: wafer pressure, frame- and wafer-suction
- 7 Optical light-sensor for transparent tape detection
- 8 Micro-switch for transparent tape detection
- 9 Optional: Table heater control



STANDARD

- RAD-2500m/12: Handling of wafer sizes 300mm, 200mm and 150mm
- RAD-2500m/8: Handling of wafer sizes 200mm, 150mm, 125mm, 100mm
- Mounting of pre-cut tape
- Automated Tape Tension Control (TTC) for reliable mounting results
- Displays for wafer-mounting pressure, as well as for frame- and wafer-suction



OPTIONS

- Non-contact wafer-tables, as well as manifold other table-design options
- Wafer-table heating function, up to 100°C
- Optical & mechanical sensors to detect pre-cut tape sheets & ensure repeatable mounting quality
- Upright and customized tape-mounting system for thick & stiff PET tapes
- CE compliance
- Inline pre-cut unit for processing of roll-type tape
- Ionizers to enhance anti-ESD performance



Adwill

Tape x Equipment

Contact us.
We look forward
to meeting you!



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